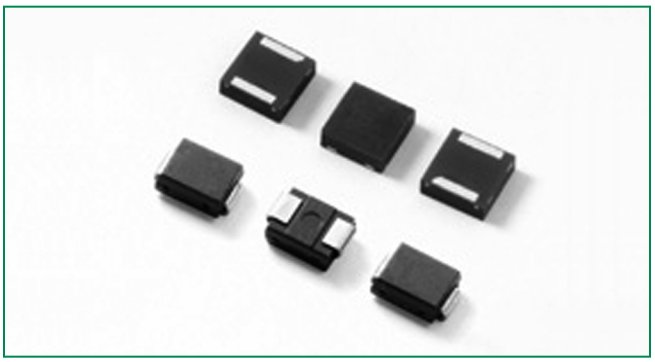
THE DATASHEET OF

PLED13S

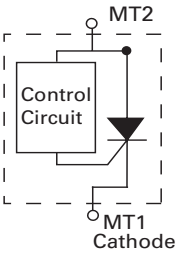
HF RoHS PLED Series



Agency Approvals - PENDING

Agency	Agency File Number
	E133083

Schematic Symbol



Description

The open LED protector provides a switching electronic shunt path when an LED in an LED array fails as an open circuit. This ensures that the entire array of LEDs will continue to function even if a single LED in the array does not. This provides higher reliable lighting functions in applications such as headlights, aircrafts, aircraft runway lighting, roadside warning lights, etc. This device is compatible with one, two and three watt LEDs that have a nominal 3V forward characteristic. The PLED series is available in two surface mount packages, the DO-214 and the Quad Flat Pak No-lead (QFN). The QFN's low profile, chip scale package (CSP) is ideal for dense board applications.

Features & Benefits

- Fast switching
- Automatically resets after power cycle
- Available in low profile, small footprint QFN and Standard DO214AA packages
- Compatible with industrial lighting environments
- Compatible with PWM dimming speeds of up to 10 KHz
- RoHS compliant and halogen-free

Electrical Characteristics

Part Number	Marking	V_{BR} breakdown		V_{DRM} breakdown	I_H	I_S	I_T@V_T	V_T @ I_T = 1 Amp	Critical rate of rise dV/dt
		Volts		Volts	mAmps	mAmps	Amps	Volts	Volts
		Min	Max	Min	Min	Max	Max	Max	Max
PLED6Q12	PL6	6	16	6	5	100	1.0	1.5	250V/µs
PLED6S	PL6	6	16	6	5	100	1.0	1.5	250V/µs
PLED9Q12	PL9	9	18	9	5	100	1.0	1.5	250V/µs
PLED9S	PL9	9	18	9	5	100	1.0	1.5	250V/µs
PLED13Q12	PL13	13	26	13	5	100	1.0	1.5	250V/µs
PLED13S	PL13	13	26	13	5	100	1.0	1.5	250V/µs
PLED18Q12	PL18	18	33	18	5	100	1.0	1.5	250V/µs
PLED18S	PL18	18	33	18	5	100	1.0	1.5	250V/µs

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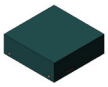
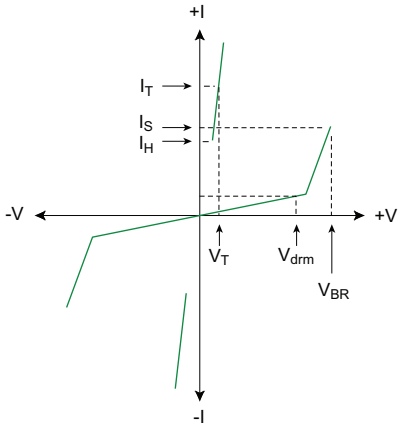
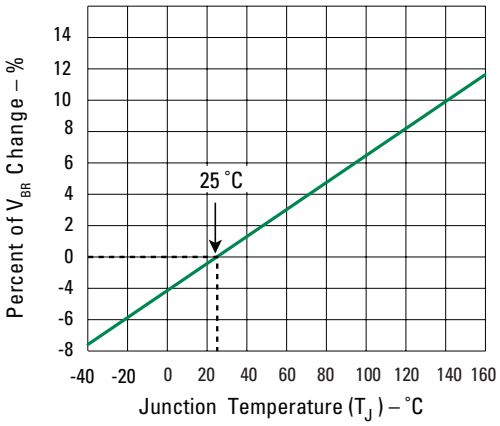
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
QFN 3x3  DO-214	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	DO-214: 90 QFN: 120	°C/W

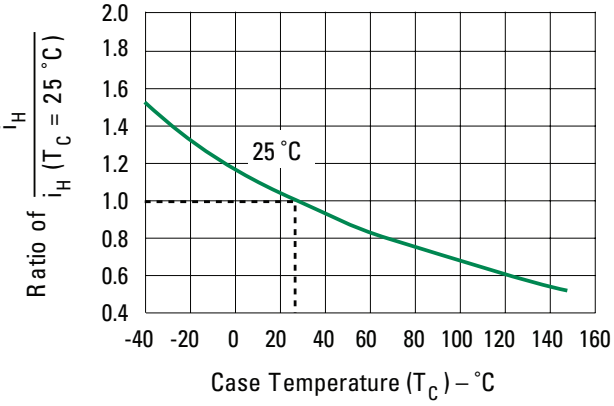
V-I Characteristics



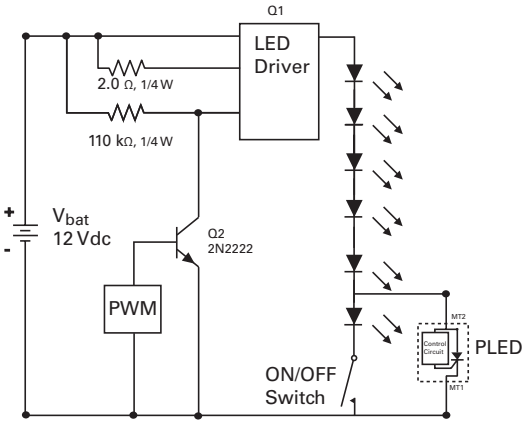
V_{BR} vs. Junction Temperature



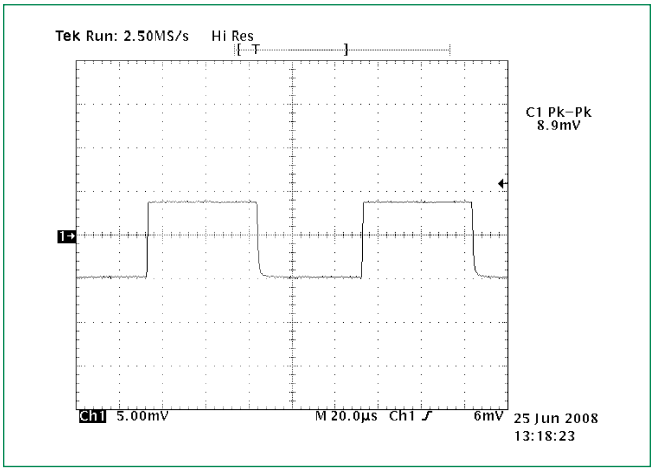
Normalized DC Holding Current vs. Case Temperature



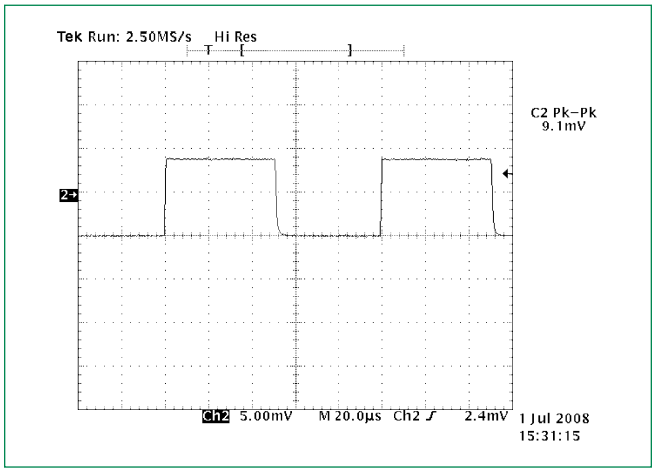
LED Interference Test Circuit



6 LEDs in Series 50% Duty Cycle 10Khz

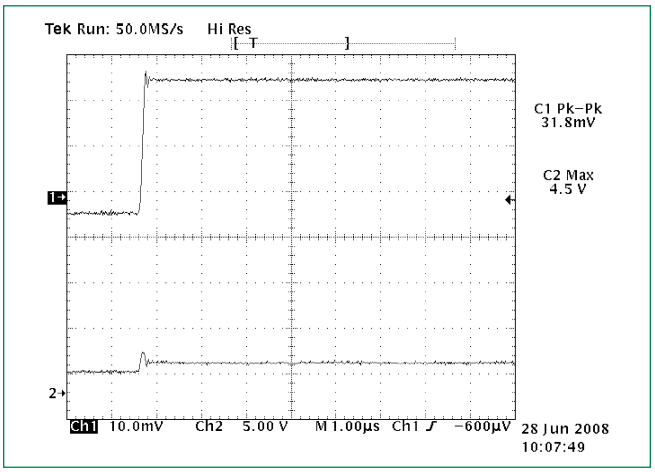


5 LEDs and 1 PLED in Series 50% Duty Cycle 10Khz



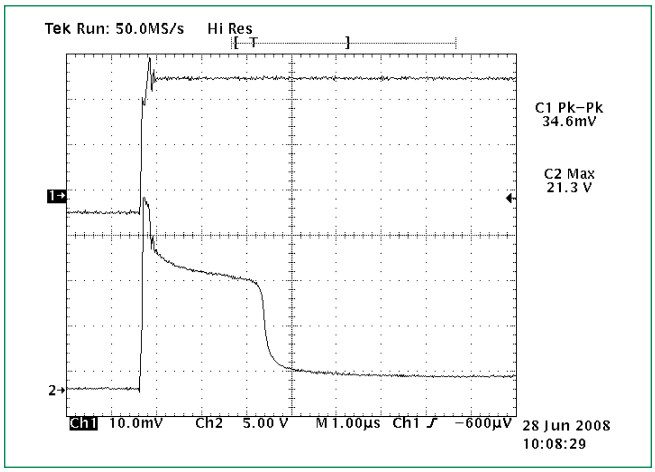
Note: These two graphs show the current magnitude through the LED string with and without the PLED included. There is no noticeable effect on the LED current magnitude when the PLED is included in the circuit as compared to the LED current magnitude when the PLED is not in the circuit. (The conversion factor for the test measurement in the graphs above is 10mA/mV for the Pearson coil measurement, therefore, the current magnitude in the first figure is 10mA*8.9 = 89mA, while the second figure is 91mA.)

PLED in the Off-State 10Khz



Channel 1: current through LEDs (318 mA)
Channel 2: voltage across PLED device (4.5 V)

PLED device zeners and then turns fully on 10Khz



Channel 1: current through LEDs (346 mA) and PLED device once it is fully turned on 2.5 µsec later
Channel 2: voltage across PLED device (21.3 V before PLED crowbars with 2 V drop)

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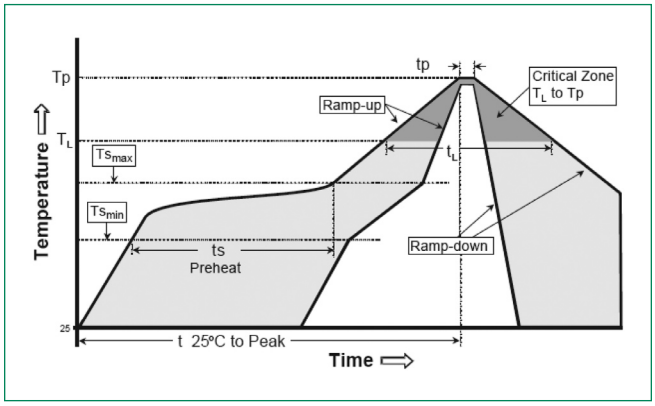
Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes max
Do not exceed		260°C



Physical Specifications

Terminal Material	Copper Alloy
Terminal Finish	100% Matte Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

Environmental Specifications

High Temperature Voltage Blocking	MIL-STD-750: Method 1040, Condition A 80% min V_{DRM} (VAC-peak), 150°C, 504 hours
Temperature Cycling	MIL-STD-750: Method 1051 -65°C to 150°C, 15-minute dwell, 100 cycles
Biased Temperature & Humidity	EIA/JEDEC: JESD22-A101 52VDC, 85°C, 85%RH, 1008 hours
High Temperature Storage	MIL-STD-750: Method 1031 150°C, 1008 hours
Low Temperature Storage	-65°C, 1008 hours
Thermal Shock	MIL-STD-750: Method 1056 0°C to 100°C, 5-minute dwell, 10-second transfer, 10 cycles
Resistance to Solder Heat	MIL-STD-750: Method 2031 260°C, 10 seconds

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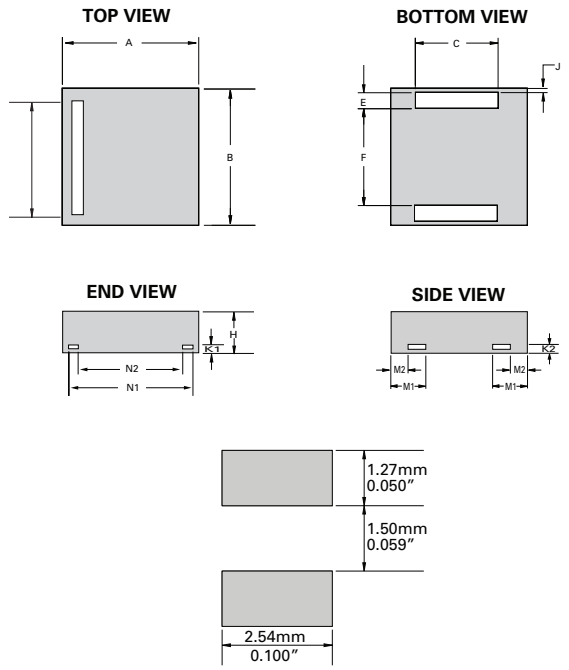
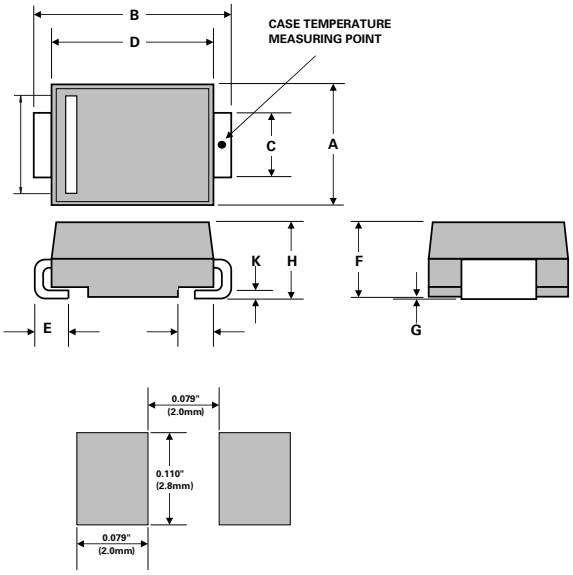
Dimensions - QFN (3x3) Package



Recommended solder pad layout
(Reference Only)

Dimensions	Inches			Millimeters		
	Min	Typ	Max	Min	Typ	Max
A	0.114	0.118	0.122	2.900	3.000	3.100
B	0.114	0.118	0.122	2.900	3.000	3.100
C	0.075	0.079	0.083	1.900	2.000	2.100
E	0.011	0.015	0.019	0.285	0.385	0.485
F	0.076	0.080	0.084	1.930	2.030	2.130
H	0.035	0.039	0.043	0.900	1.000	1.100
J	0.000	0.004	0.008	0.000	0.100	0.200
K1	0.004	0.008	0.012	0.100	0.200	0.300
K2	0.004	0.008	0.012	0.100	0.200	0.300
M1	0.056	0.060	0.064	1.143	1.530	1.630
M2	0.038	0.042	0.046	0.970	1.070	1.170
N1	0.096	0.100	0.104	2.440	2.540	2.640
N2	0.082	0.086	0.090	2.080	2.180	2.280

Dimensions - DO-214 AA Package



Recommended
Soldering Pad Outline

Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.130	0.156	3.30	3.95
B	0.201	0.220	5.10	5.60
C	0.077	0.087	1.95	2.20
D	0.159	0.181	4.05	4.60
E	0.030	0.063	0.75	1.60
F	0.075	0.096	1.90	2.45
G	0.002	0.008	0.05	0.20
H	0.077	0.104	1.95	2.65
K	0.006	0.016	0.15	0.41

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Part Numbering System

PLED X Q12

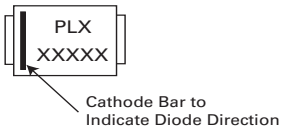
TYPE
PLED: LED Protector

V_{DRM}
6 Volts
9 Volts
13 Volts
18 Volts

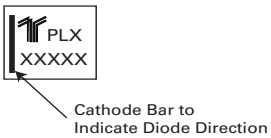
PACKAGE TYPE
Q12: 3.0x3.0mm QFN
S: DO-214

Part Marking System

DO-214



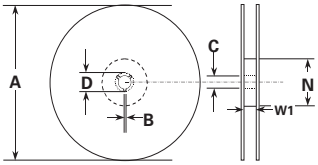
QFN



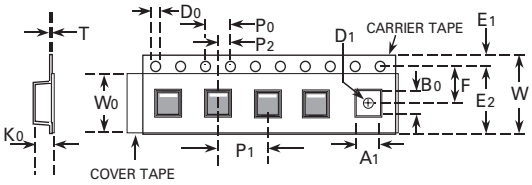
Packaging

Package	Description	Packaging Quantity	Industry Standard
Q12	QFN 3x3	5000	EIA-481-1
S	DO-214	2500	EIA-481-1

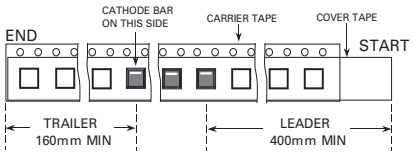
Tape and Reel Specification - QFN (3x3)



Reel Dimension



Tape Dimension Items



Leader and Trailer Dimension of the Ttape

Symbols	Description	Inches		Millimeters	
		Minimum	Maximum	Minimum	Maximum
A	Reel Diameter	N/A	12.992	N/A	330.0
B	Drive Spoke Width	0.059	N/A	1.50	N/A
C	Arbor Hole Diameter	0.504	0.531	12.80	13.50
D	Drive Spoke Diameter	0.795	N/A	20.20	N/A
N	Hub Diameter	1.969	N/A	50.00	N/A
W1	Reel Inner Width at Hub	0.488	0.567	12.40	14.40
A0	Pocket Width at bottom	0.126	0.134	3.20	3.40
B0	Pocket Length at bottom	0.126	0.134	3.20	3.40
D0	Feed Hole Diameter	0.059	0.063	1.50	1.60
D1	Pocket Hole Diameter	0.059	N/A	1.50	N/A
E1	Feed hole Position 1	0.065	0.073	1.65	1.85
E2	Feed hole Position 2	0.400	0.408	10.15	10.35
F	Feed hole center-Pocket hole	0.215	0.219	5.45	5.55
K0	Pocket Depth	0.039	0.051	1.00	1.30
P0	Feed hole Pitch	0.153	0.161	3.90	4.10
P1	Component Spacing	0.311	0.319	7.90	8.10
P2	Feed hole center-Pocket hole	0.077	0.081	1.90	2.06
T	Carrier Tape Thickness	0.010	0.014	0.25	0.35
W	Embossed Carrier Tape Width	0.453	0.484	11.50	12.30
W0	Cover Tape Width	0.358	0.366	9.10	9.30

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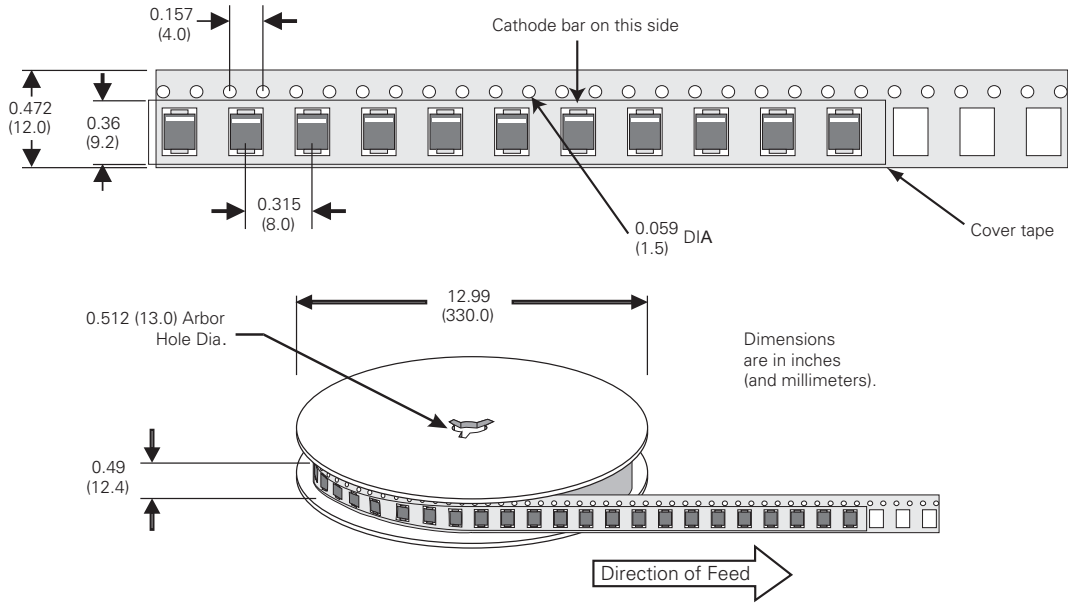
DO-214 Embossed Carrier Reel Pack (RP)

Meets all EIA-481-1 Standards



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